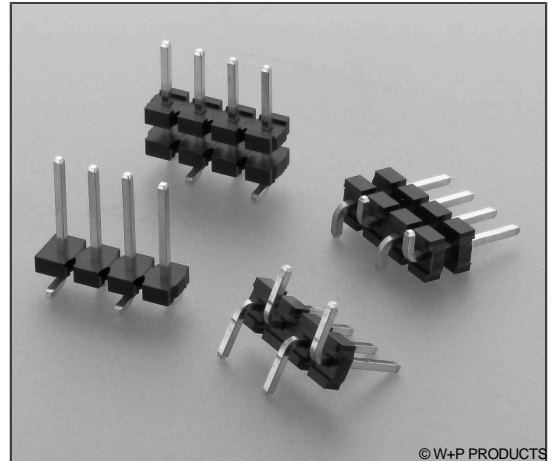


# 9850 / 9860

## SMT-Stiftleisten RM 5,08mm, stehend – Power-Kontakte SMT Pin Headers, 5.08mm Pitch, Vertical – Power Contacts

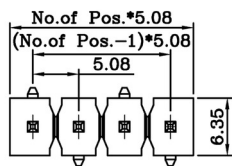
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift 1,14mm, Kupferlegierung <i>1.14mm square pin, copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni <i>Acc. to options (see below), over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC
Nennstrom <i>Current Rating</i>	7,9 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +105 °C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

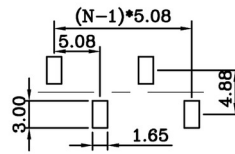
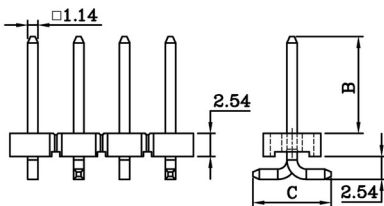


© W+P PRODUCTS

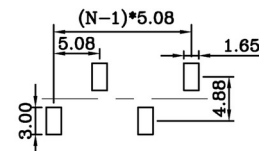
Passende Buchsenleisten:  
Compatible Female Headers:  
395/396 3950 3960



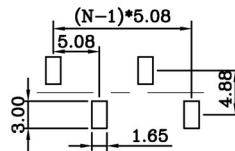
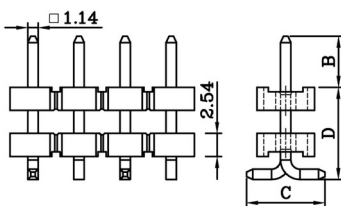
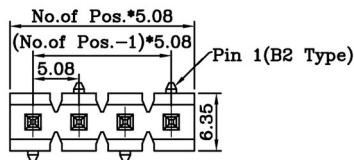
Pin 1 (B1 Type)



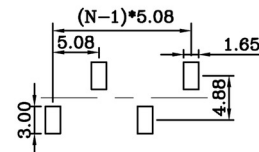
RECOMMENDED PCB LAYOUT (B1 Type)



RECOMMENDED PCB LAYOUT (B2 Type)



RECOMMENDED PCB LAYOUT (B1 Type)



RECOMMENDED PCB LAYOUT (B2 Type)

# 9850 / 9860

SMT-Stiftleisten RM 5,08mm, stehend – Power-Kontakte

SMT Pin Headers, 5.08mm Pitch, Vertical – Power Contacts

Series*	Type*	Contacts*	Rows	Layout*	Plating	Packaging*
<b>9850</b>	<b>10</b>	<b>05</b>	<b>1</b>	<b>1</b>	<b>50</b>	<b>ST</b>
9850 Single Body 9860 Dual Body	10 B=10,72 C=8,64mm (9850) 20 B=12,24 C=8,38mm (9850) 30 B=5,64 C=8,64 D=10,16mm (9860)	02-20		1 Layout B1 2 Layout B2	50 Verzinkt Tin plated	ST PPST PPTR (Option)

\* Dies ist ein **Bestellbeispiel** -  
bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** -  
please replace by your specifications.

#### Lieferformen / Packaging Options:

**ST** In Stangen / In tubes

**PPST** In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads

**PPTR (Option)** Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

